

MOSFET Compact Modeling Issues for Low Temperature (77 K - 200 K) Operation

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Outline

- **Introduction**
- **CMOS process and characterization**
- **Results concerning standard and specific effects at low temperature**
- **Compact modeling issues at low temperature**
- **Conclusion**

Introduction: aim of this work

- ✓ **Design of hybrid CMOS read-out circuits for night vision with high perf. IR detectors**
- ✓ **Difficulties: low temperature (LT) & analog (weak/moderate inversion) circuits**
- ✓ **EKV2.6 used for IC design with 0.8 ... 0.35 μm CMOS**
- ✓ **More and more transistors in the pixel, need for advanced CMOS processes**
- ✓ **0.18 μm process: new effects, e.g. INWE (STI), DITS (pockets)**
- ✓ **Need an accurate compact model, which model: EKV3 (charge), HiSIM2 or PSP (surface potential)?**

CMOS process & characterization

Process

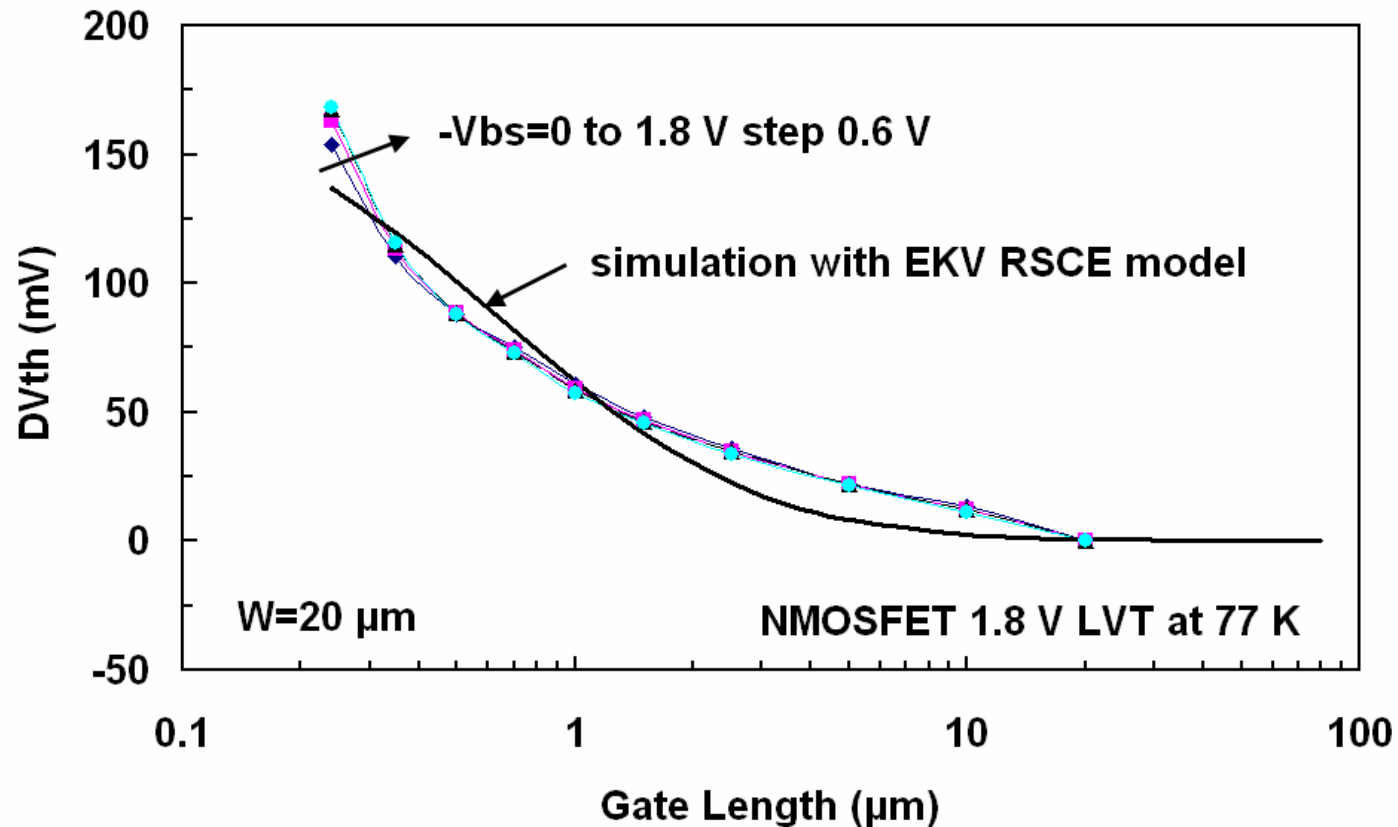
- ✓ Commercial process, optimized for room temperature
- ✓ 0.18 μm - 1.8 V ($T_{\text{ox}}=3.3$ nm) & 0.35 μm - 3.3 V (6.5 nm)
- ✓ Different transistors: standard (STD), low V_{th} (LVT), zero V_{th} (ZVT)

Characterization

- ✓ 1st step before parameter extraction & optim. using a compact model
- ✓ Short channel effects
- ✓ Narrow width effects
- ✓ Evolution of std. effects, temperature range: 77 K – 300 K
- ✓ Specific effects at LT ?

Reverse short-channel effect (RSCE)

$$DV_{th} = V_{th} - V_{th}(L=20 \mu\text{m})$$

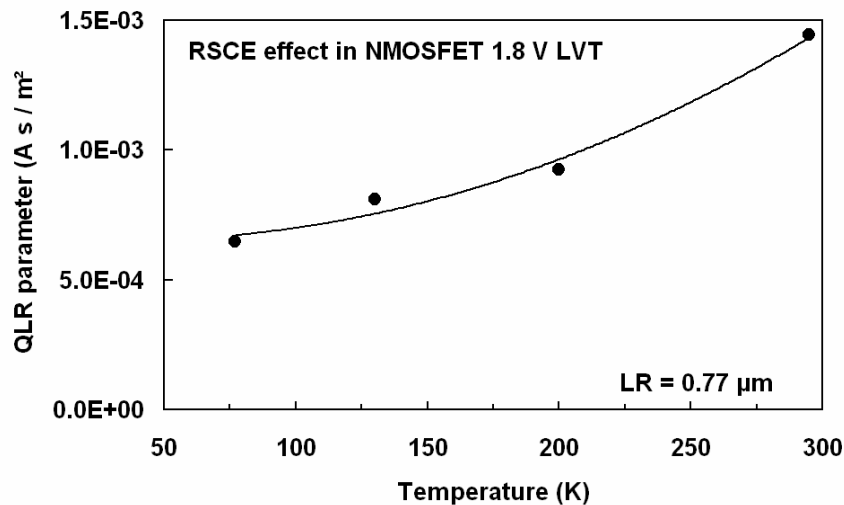
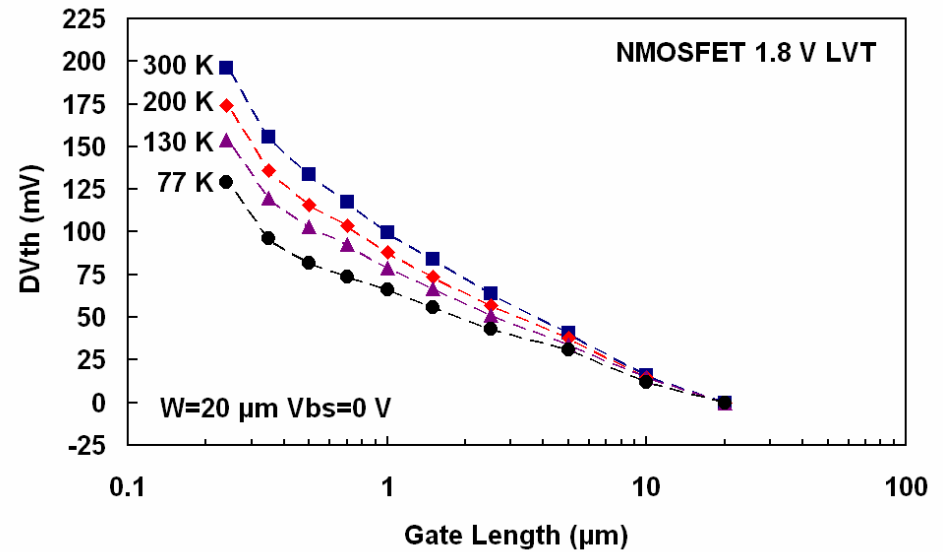


Standard RSCE effect well modeled in EKV2.6 and EKV3

Temperature modeling of RSCE effect

- RSCE reduced by temperature lowering
- Interpretation: V_{th} function of $2 \Phi_F$

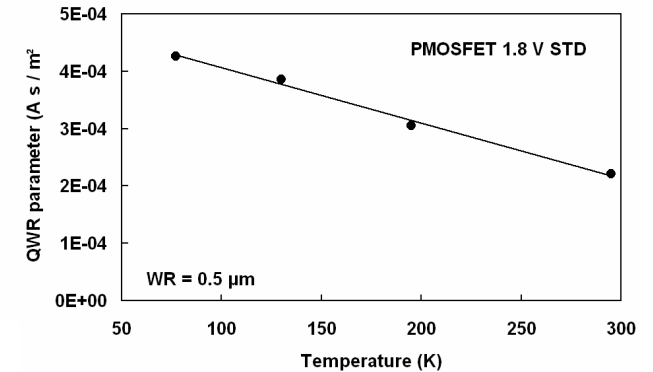
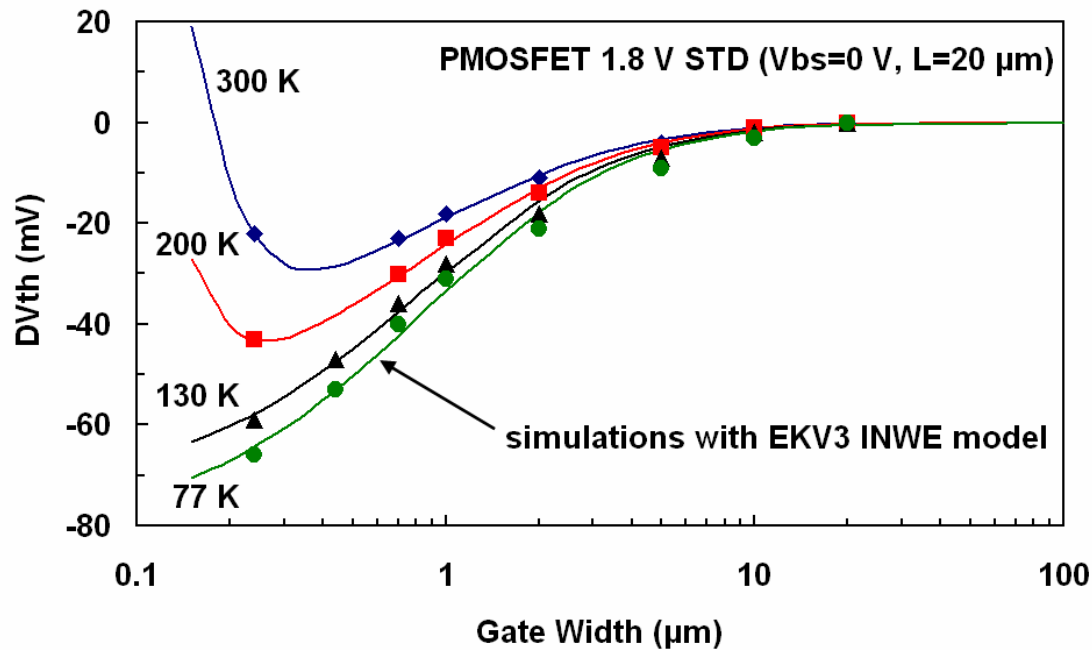
$$\Phi_F(L) = \frac{kT}{q} \ln \left(\frac{N_{ch}^{eff}(L)}{n_i} \right)$$



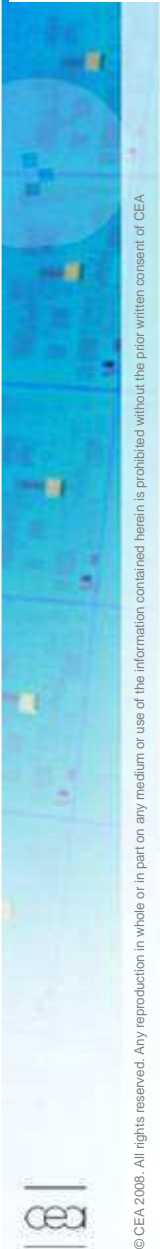
Evolution of QLR with T:
quadratic law

EKV2.6 and EKV3
model parameter

Inverse narrow width effect (INWE)

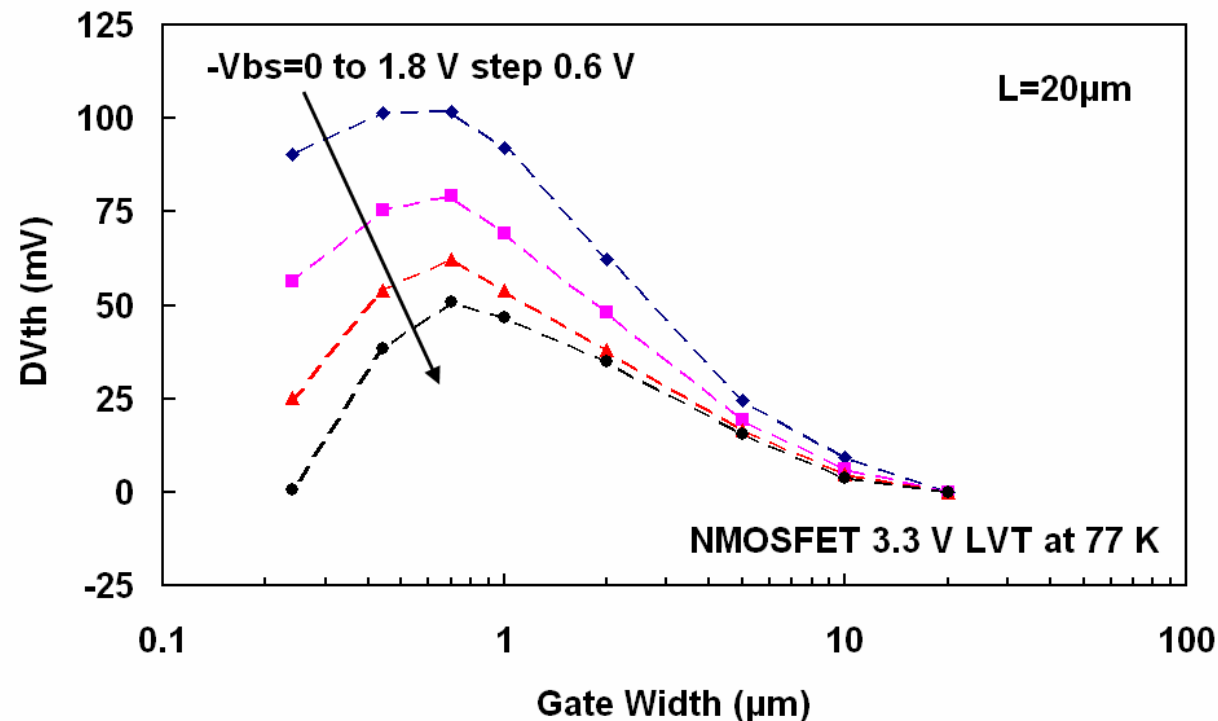


- INWE due to STI
- Increased by temperature lowering
- Not modeled in EKV2.6, but modeled in EKV3
- Linear evolution with temperature of QWR, the EKV3 model parameter



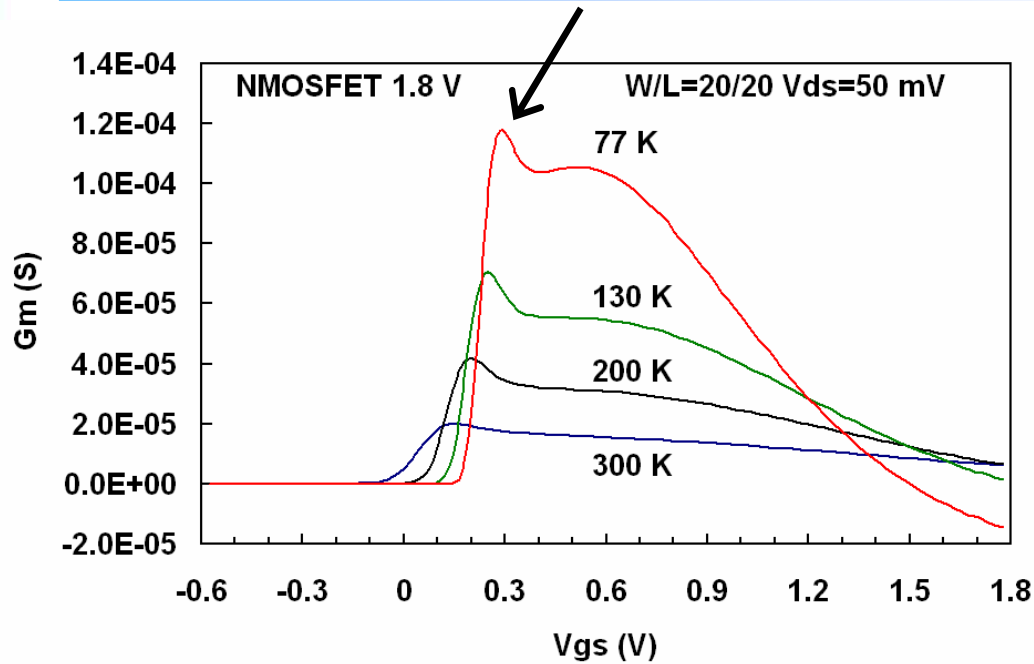
Specific effects at low temperature ?

Anomalous INWE



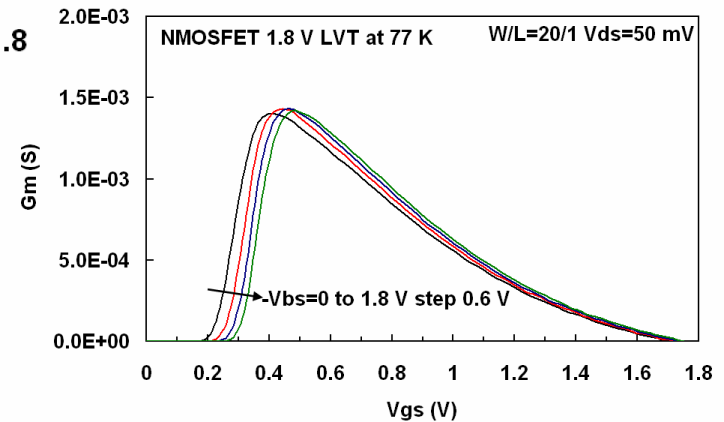
- Observed only in NMOSFETs, also at 300 K
- Max DVth: 20 mV at 300 K, 60 mV at 130 K ($V_{bs} = 0$ V)
- Origin ?
- Anomalous effect not modeled in EKV3, HiSIM or PSP

Observation of a G_m peak at LT



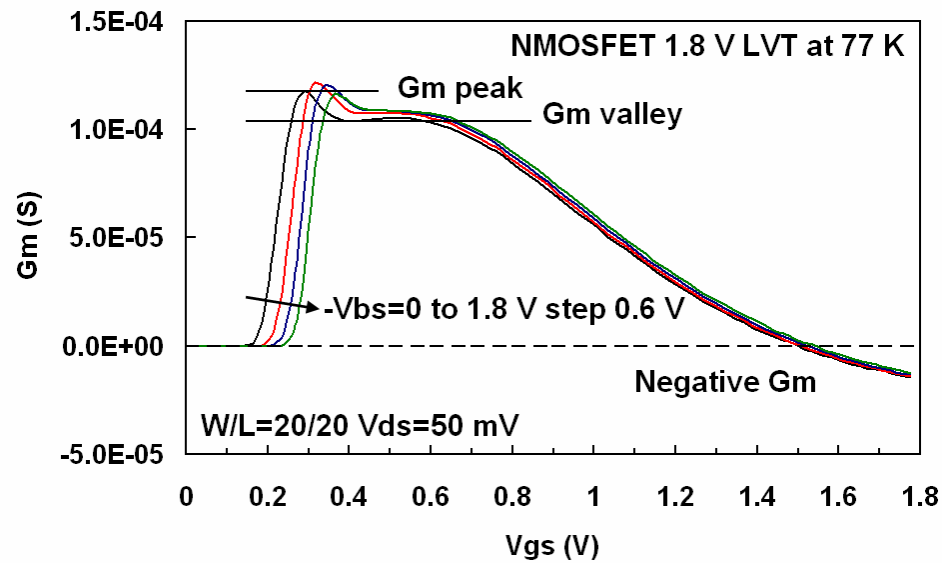
$L=20 \mu\text{m}$

$L=1 \mu\text{m}$



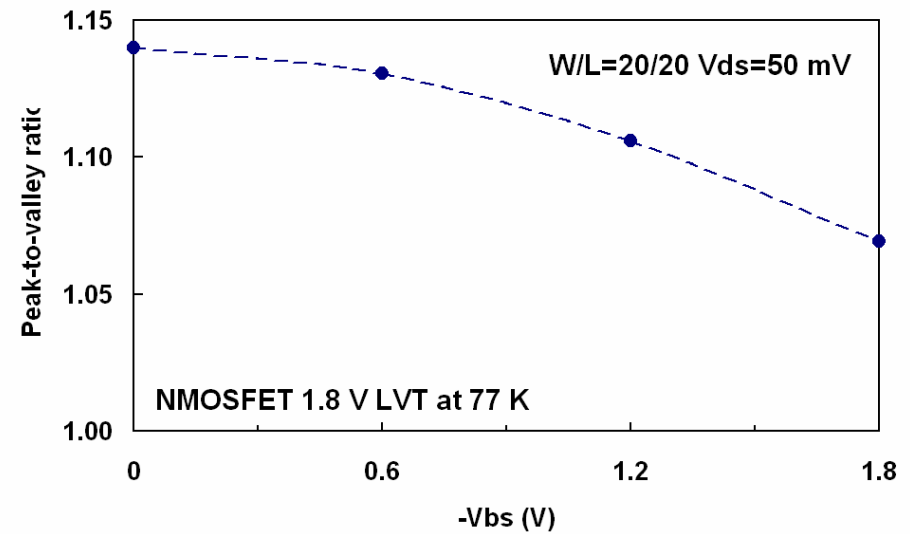
Peak observed in moderate inversion, only on LVT NMOS transistors (lowly doped), only on long channels, not on short channels

Origin of the Gm peak ?



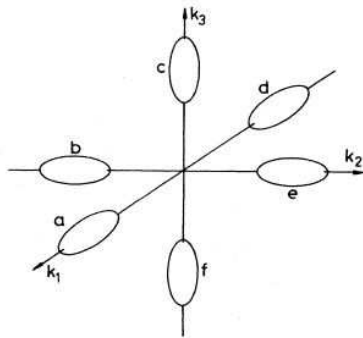
Measurements done at different Vbs

The peak-to-valley ratio tends to 1 at high Vbs



Tentative interpretation of the Gm peak

- 2D-quantization in the inversion layer due to surface field F_s
- Formation of energy subbands



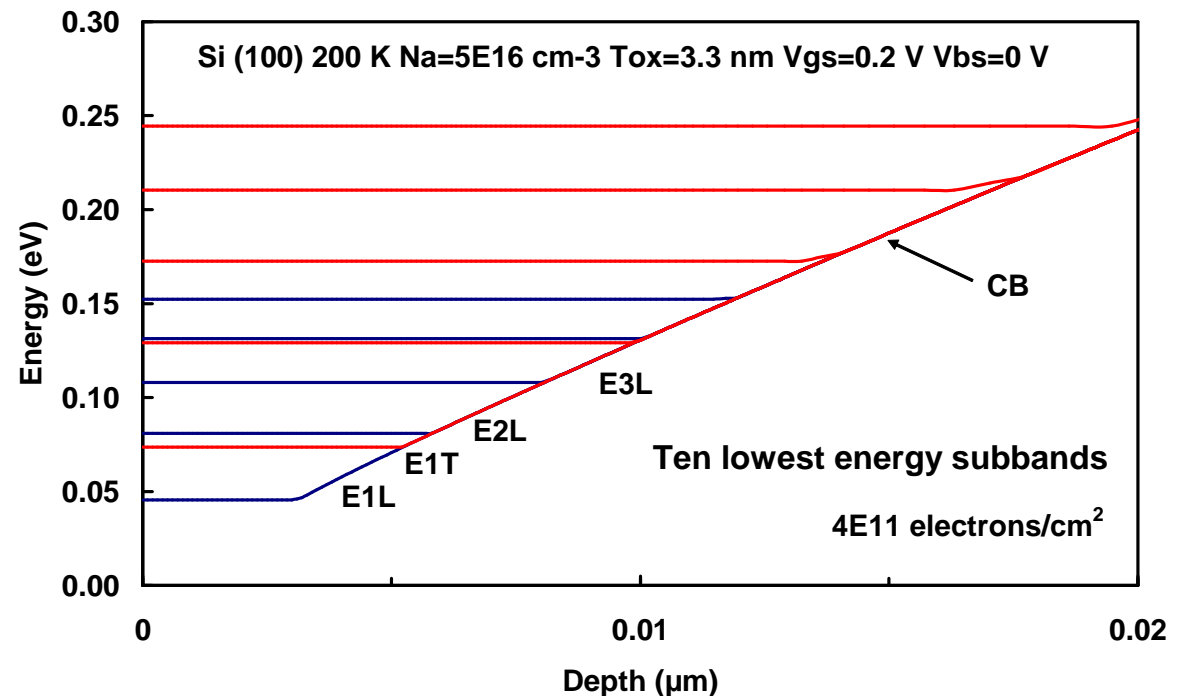
$$m_T = 0.19 m_0$$

$$m_L = 0.916 m_0$$

FIG. 5. Schematic constant-energy surfaces for the conduction band of silicon, showing six conduction-band valleys in the $\langle 100 \rangle$ direction of momentum space. The band minima, corresponding to the centers of the ellipsoids, are 85% of the way to the Brillouin-zone boundaries. The long axis of an ellipsoid corresponds to the longitudinal effective mass of electrons in silicon, $m_l = 0.916m_0$, while the short axes correspond to the transverse effective mass, $m_t = 0.190m_0$.

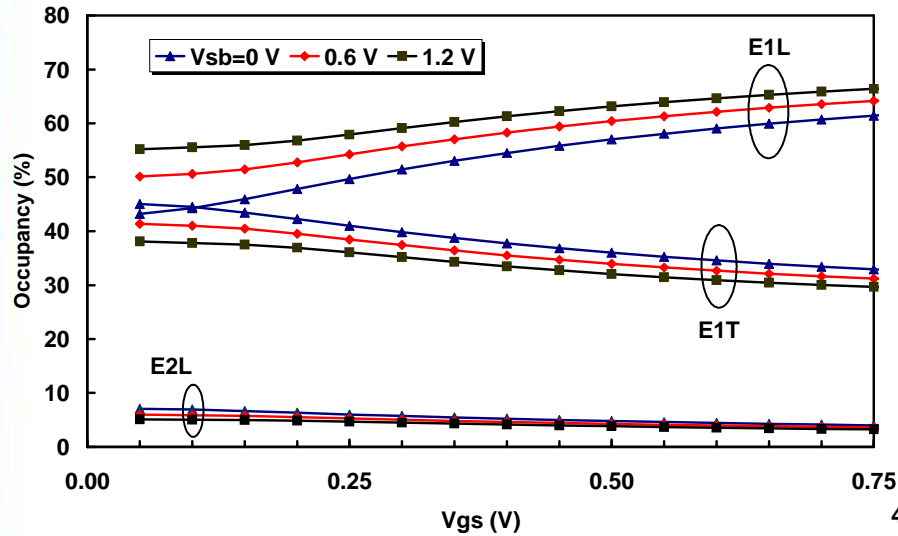
(Ando, 1982)

Poisson-Schrödinger simulations



Poisson-Schrödinger simulations

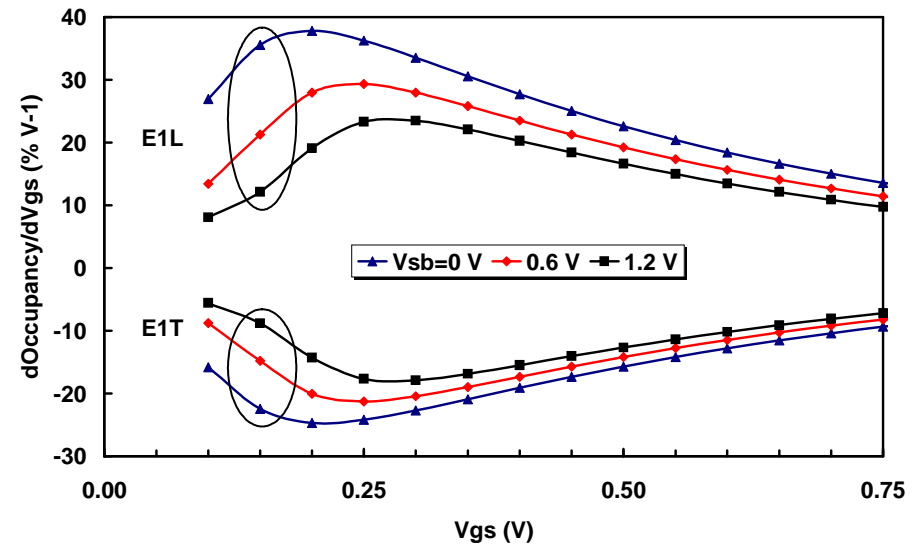
Influence of substrate biasing



$V_{sb} \nearrow \quad Q_b \nearrow \quad F_s \nearrow \quad \%E1L \nearrow$

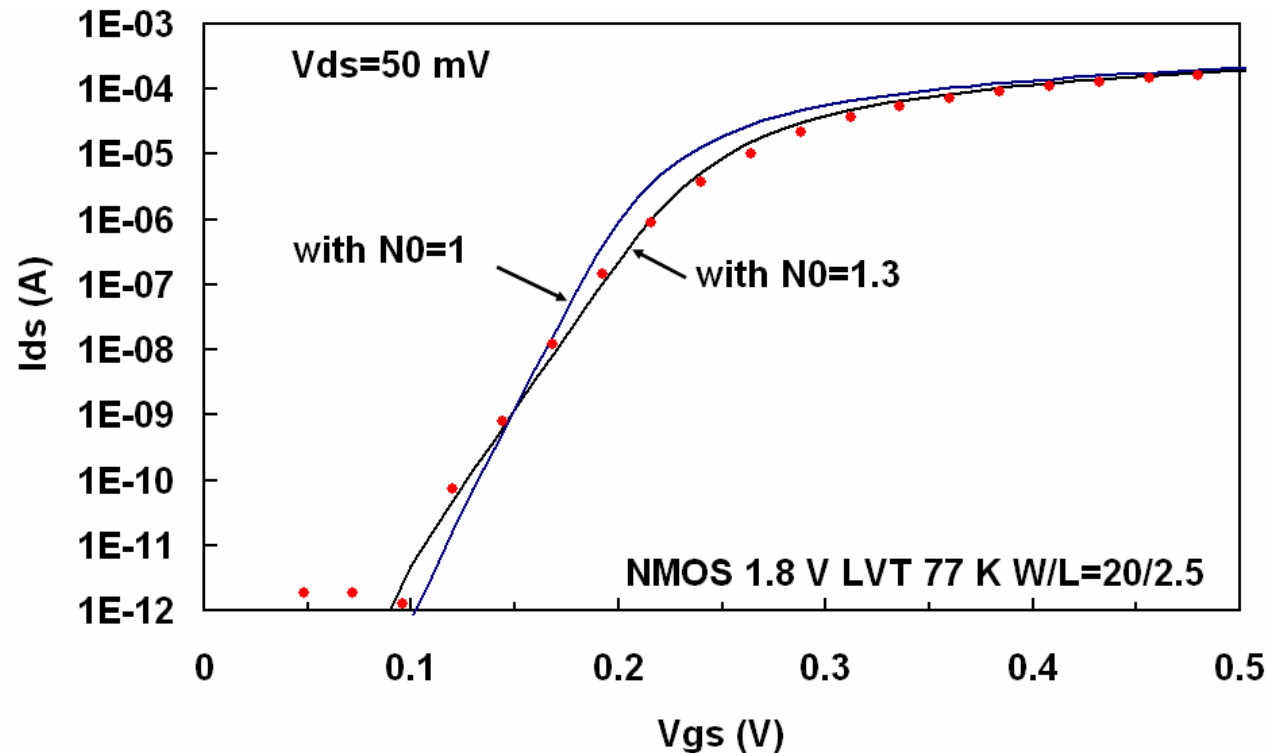
$I_{ds} \approx N_{inv}$

$G_m \approx dN_{inv}/dV_{gs}$



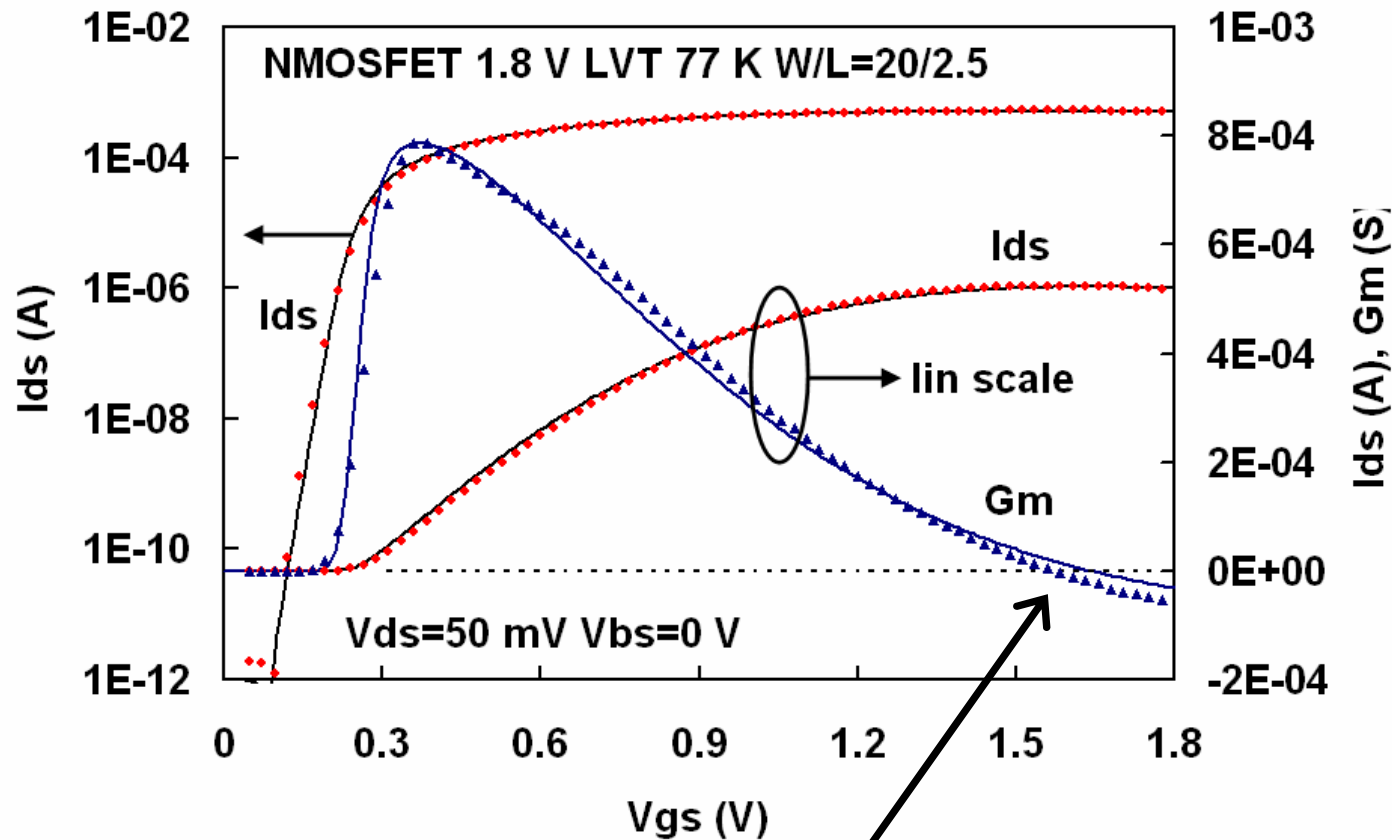
$T=200 \text{ K}$ $N_a=5 \times 10^{16} \text{ cm}^{-3}$
 $T_{ox}=3.3 \text{ nm}$

Subthreshold slope degradation at LT



- **$S \approx 20\text{-}25$ mV/dec. at 77 K for long channels: higher than that predicted**
- **Influence of interface traps**
- **Need for a new parameter: N_0 in EKV3, CT in PSP, PTHROU in HiSIM2**

Negative Gm and EKV3 simulation



- Negative Gm on some transistors at LT
- Mobility model (incl. Coulomb scatt., phonons & SR) accounts for negative Gm observed on some transistors

Others effects & modeling issues

- **Freeze-out in LDD zones: strong impact during parameter extraction at low V_{ds} , not modeled in EKV, HiSIM or PSP**
- **DITS and G_{ds} degradation in long channels (pockets): important for analog devices, but data only for room temperature**
- **Temperature modeling of GIDL (linear, STBGIDL parameter in PSP)**

Conclusion

- **Specific effects observed at low temperature, e.g.:**
 - ✓ Quantization in inversion layer \Leftrightarrow Gm peak in some transistors
 - ✓ Freeze-out effects in LDD
 - ✓ Subthreshold slope degradation
 - ✓ Anomalous INWE
- **Must be taken into account for accurate parameter extraction & modeling**
- **An improved compact model already needed for 0.18 μm technology**
- **EKV3 is a good candidate**, but should be improved for accurate low temperature modeling and circuit simulations
- **HiSIM2 and PSP to be evaluated at LT**